

REMARKS

Claims 1-4 have been cancelled without prejudice, and claims 5-11 have been added. No new matter has been added by virtue of the amendments. For instance, support for the new claims appears e.g. at page 7, line 21 through page 9, line 10; page 10, lines 14-22; Example 3 on page 18; and the original claims of the application.

An Information Disclosure Statement is being filed under separate cover.

Claims 1-4 were rejected under 35 U.S.C. 102(e) over Chen (U.S. Patent 6,197,181). The rejection is traversed.

Applicants' independent claim 5 calls for electrolytically depositing copper into the trenches or via holes of a silicon wafer substrate from an electroplating composition that comprises copper ions and one or more complexing agents for the copper ions and having a pH of from 4 to 8.4.

Electroplating at a pH of 8.4 is specifically demonstrated in Example 3 on page 18 of the application. Examples 1 and 2 of the application also demonstrate electroplating in Applicants' claimed pH range. Notably good results using those compositions of Examples 1-3 are disclosed at pages 21-22 of the present application.

The cited Chen patent does not teach or suggest such an electroplating bath as Applicants claim. In fact, Chen specifically teaches away from such a plating bath and reports use of baths having a pH of 9 or higher (more basic). See, for instance, Chen at column 5, lines 51-64. In the examples of Chen, the reported compositions have pH values in excess of 9. See Chen at column 7, lines 55-60.

Applicants' independent claim 9, as well as dependent claims 6, 7 and 10, call for electrolytically depositing copper into the trenches or via holes of a silicon wafer substrate from an electroplating composition that comprises copper ions and one or more complexing agents for the copper ions,

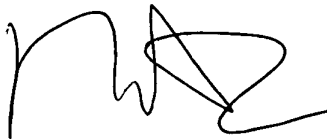
wherein the one or more complexing agents are chosen from among an aminealkanol compound, cyclic acid-imide compound, and an organic phosphonic acid compound.

Such complexing agents are not disclosed or otherwise suggested in the Chen citation.

In view thereof, reconsideration and withdrawal of the rejection are requested.

It is believed the application is in condition for immediate allowance, which action is earnestly solicited.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'P. Corless', with a stylized flourish at the end.

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